



# FCT Solder

## ECHA REACH COMPLIANCE

FCT Solder products are in compliance with ECHA REACH requirements for all substances of very high concern (SVHC). Our products do not contain any of the ingredients in the candidate list table, with some exceptions which are listed below.

<https://echa.europa.eu/candidate-list-table>

This list has been updated June 12<sup>th</sup>, 2022 per (EC 1907/2006).

Products which do contain materials in the SVHC candidate list.

| Product                       | Chemical                                          | CAS#      | Concentration (% wt.)                                                         |
|-------------------------------|---------------------------------------------------|-----------|-------------------------------------------------------------------------------|
| WS890                         | 2-[[4-(2,4,4-trimethylpentan-2-yl)phenoxy]ethanol | 9002-93-1 | Flux gel (<3.0%)<br>Solder paste (0.36%)                                      |
| WS890                         | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (1.4%)<br>Solder paste (0.16%)                                       |
| NC650                         | Dibutyl phthalate (DBP)                           | 84-74-2   | Flux gel (0.79%)<br>Solder paste (0.08%)                                      |
| NL900                         | Dibutyl phthalate (DBP)                           | 84-74-2   | Flux gel (0.79%)<br>Solder paste (0.09%)                                      |
| NL900                         | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (13.1%)<br>Solder paste (1.3%)                                       |
| WS157                         | Dibutyl phthalate (DBP)                           | 84-74-2   | Flux gel (0.88%)<br>Solder paste (0.10%)                                      |
| Lead Containing Solder Pastes | Lead                                              | 7439-92-1 | 30-90% Lead is intentionally added to solder pastes at varying concentrations |
| RMA250                        | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (6.6%)<br>Solder paste (0.67%)                                       |
| NC676                         | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (7.0%)<br>Solder paste (0.72%)                                       |
| WS159                         | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (3.5%)<br>Solder paste (0.37%)                                       |
| WS888                         | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme)   | 143-24-8  | Flux gel (1.4%)<br>Solder paste (0.15%)                                       |

|                     |                                                 |           |      |
|---------------------|-------------------------------------------------|-----------|------|
| WIL-1               | Bis(2-(2-methoxyethoxy)ethyl)ether (tetraglyme) | 143-24-8  | 3.5% |
| Nitroflo Bar Solder | Lead                                            | 7439-92-1 | 37%  |

In addition, FCT Solder products do not contain carcinogenic, mutagenic, reproduction toxic substances as listed in Annex 1 to Directive 67/548/ EEC and in Annex VI to EU's CLP regulation.